



ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C256M8D3LC-12BCN/BIN/BAN							
Part Weight:		137.1mg							
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt% of Total unit wt	PPM
1	Substrate	HL-8320NXA / AUS 308	27.746	Barium Sulfate	7727-43-7	28.38%	7.874	5.74%	283800
				3-Methoxy-3-methylbutylacetate	103429-90-9	28.38%	7.874	5.74%	283800
				Dipropylene Glycol Monomethyl Ether	34590-94-8	1.16%	0.322	0.24%	11623.2
				Talc containing no asbestiform fibers	14807-96-6	0.80%	0.222	0.16%	8016
				Morpholine derivative	Trade Secret	0.40%	0.111	0.08%	4008
				Solvent naphtha(petroleum), Heavy arom	Trade Secret	0.10%	0.028	0.02%	1002
				2,4,6-Triamino-1,3,5-Triazine	Trade Secret	0.10%	0.028	0.02%	1002
				Silicon dioxide	Trade Secret	0.10%	0.028	0.02%	1002
				Diethylene Glycol Monoethyl Ether Acetate	Trade Secret	0.10%	0.028	0.02%	1002
				Naphthalene	91-20-3	0.01%	0.003	0.00%	100.2
				Trimethylbenzene	Trade Secret	0.01%	0.003	0.00%	100.2
				Epoxy Resin (MW≤700)	Trade Secret	0.01%	0.003	0.00%	100.2
				Barium Sulfate	7727-43-7	0.01%	0.003	0.00%	100.2
				Dipropylene Glycol Monomethyl Ether	34590-94-8	3.01%	0.834	0.61%	30060
				Dipentaerythritol hexaacrylate	Trade Secret	1.80%	0.500	0.37%	18036
				Dipentaerythritol pentaacrylate	Trade Secret	1.20%	0.334	0.24%	12024
				3-Methoxy-3-methylbutylacetate	103429-90-9	0.60%	0.167	0.12%	6012
				Continuous Filament Fiber Glass	65997-17-3	0.30%	0.083	0.06%	3006
				Cured thermosetting resin (including inorganic filler)	Trade secret	0.30%	0.083	0.06%	3006
				Copper	7440-50-8	30.87%	8.565	6.25%	308700
Nickel	7440-02-0	1.83%	0.508	0.37%	18300				
Gold	7440-57-5	0.52%	0.144	0.11%	5200				
2	Mold compound	CEL-9120HF	67.811	Epoxy resin	Trade Secret	5.00%	3.391	2.47%	50000
				2,2'-((2,2',5,5'-tetramethy-(1,1'-biphenyl)-4,4'-diyl)-bis(oxymethylene))-bis-oxirane	Trade Secret	5.00%	3.391	2.47%	50000
				Hardener	Trade Secret	5.00%	3.391	2.47%	50000
				Carbon Black	1333-86-4	0.20%	0.136	0.10%	2000
				Amorphous Silica 1	60676-86-0	80.80%	54.791	39.96%	808000
				Amorphous Silica 2	14808-60-7	4.00%	2.712	1.98%	40000
3	Epoxy	6202C	1.271	2-(2-Ethoxyethoxy)ethyl acetate	112-15-2	36.50%	0.464	0.34%	365000
				Butadiene, acrylonitrile polymer, carboxy-terminated, polymer with bisphenol A and epichlorohydrin	68610-41-3	28.00%	0.356	0.26%	280000
				Isodecyl alcohol, ethoxylated	61827-42-7	10.00%	0.127	0.09%	100000
				Silica Filler	112926-00-8	25.00%	0.318	0.23%	250000
				Tert-butyl peroxyneodecanoate	26748-41-4	0.50%	0.006	0.00%	5000
4	Solder ball	SnAgCu	27.526	Tin	7440-31-5	96.50%	26.563	19.37%	965000
				Silver	7440-22-4	3.00%	0.826	0.60%	30000
				Copper	7440-50-8	0.50%	0.138	0.10%	5000
5	Gold wire	Au	0.19	Gold	7440-57-5	99.99%	0.190	0.14%	999900
				Others	Trade Secret	0.01%	0.000	0.00%	100
6	Die	Chip	12.556	Silicon	7440-21-3	100.00%	12.556	9.16%	1000000
						600.00%	137.100	100.00%	6000000